

DESCRIPTION

The fundamental of SP6019 synchronous rectifier (SR) driver IC is based on our U.S. patented methods that utilize the principle of "prediction" logic circuit. The IC deliberates previous cycle timing to control the SR in present cycle by "predictive" algorithm that makes adjustments to the turn-off time, in order to achieve maximum efficiency and avoid cross-conduction at the same time. Specially, SP6019 is designed for Forward.

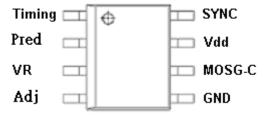
APPLICATIONS

- Servers & workstations
- Storage area network power supplies
- Telecommunication converters
- Embedded systems
- Industrial & commercial systems using high current processors

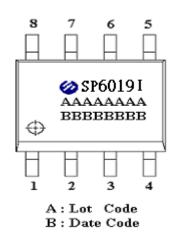
FEATURES

- Offers efficiency improvement over Schottky Diode (depends on drive configuration of the SR).
- Drives all Power MOSFET.
- Prediction gate timing control.
- Minimum MOSFET body diode conduction.
- Operating frequency up to 400 KHz.
- Synchronize to transformer secondary voltage waveform.

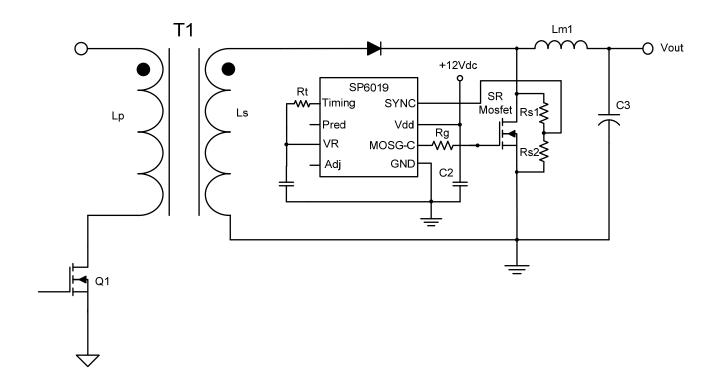
PIN CONFIGURATION (SOP-8)



PART MARKING



TYPICAL APPLCATION CIRCUIT

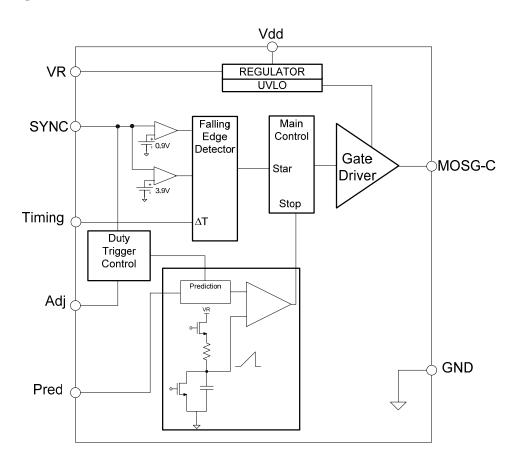


PIN DESCRIPTION

| Pin | Symbol | Description | | | |
|-----|--------|---|--|--|--|
| 1 | Timing | Discontinuous current filter timing adjustment resistor connection. | | | |
| 2 | Pred | Capacitor to store previous cycle timing for SR MOSFET. | | | |
| 3 | VR | Voltage Regulator. | | | |
| 4 | Adj | Trigger point adjustment for Dynamic state. | | | |
| 5 | GND | Ground connection. | | | |
| 6 | MOSG-C | Catch MOSFET gate drive. | | | |
| 7 | Vdd | DC supply voltage. | | | |
| 8 | SYNC | Synchronized signal from the V _{DS} of SR MOSFET. | | | |



BLOCK DIAGRAM



ORDERING INFORMATION

| Part Number | Package | Part Marking |
|-------------|---------|-----------------|
| SP6019S8RGB | SOP-8 | SP6019 I |
| SP6019S8TGB | SOP-8 | SP6019 I |

※ SP6019S8RGB: 7" Tape Reel; Pb − Free; Halgon − Free

※ SP6019S8TGB: Tube; Pb − Free; Halgon − Free

ABSOULTE MAXIMUM RATINGS (TA=25°C, unless otherwise specified.)

The following ratings designate persistent limits beyond which damage to the device may occur.

| Symbol | Parameter | Value | Unit |
|------------------|---|------------|------------------------|
| V_{dd} | DC Supply Voltage | 16 | V |
| I_{OUT} | Peak Source Current (Pulsed) | 1 | A |
| | Peak Sink Current (Pulsed) | 1 | A |
| P_{D} | Power Dissipation @ $T_A=85^{\circ}C$ (*) | 0.25 | W |
| T _J | Operating Junction Temperature Range | -40 to125 | $^{\circ}\!\mathbb{C}$ |
| T_{STG} | Storage Temperature Range | -40 to 150 | $^{\circ}\!\mathbb{C}$ |
| T_{LEAD} | Lead Soldering Temperature for 5 sec. | 260 | $^{\circ}\!\mathbb{C}$ |

THERMAL RESISTANCE

| Symbol | Parameter | Value | Unit |
|--------|--|-------|------|
| Rөjc | Thermal Resistance Junction – Case (*) | 45 | °C/W |

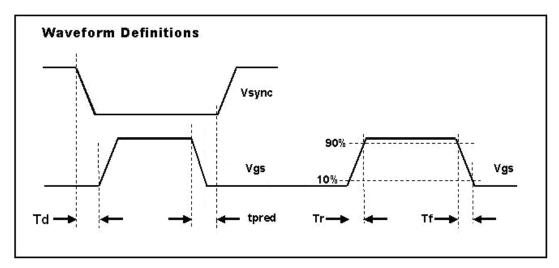
^(*) The power dissipation and thermal resistance are evaluated under copper board mounted with free air conditions.

ELECTRICAL CHARACTERISTICS

 $(T_A=25^{\circ}\text{C}, V_{dd}=12\text{V}, \text{Freq.}=300 \text{ KHz}, \text{Duty Cycle}=50\%, \text{unless otherwise specified.})$

| Symbol | Parameter | Conditions | Min. | Тур. | Max. | Unit |
|--------------|-----------------------|--------------------------------|------|------|------|------|
| SUPPLY IN | PUT | | - | | | - |
| Inn | Complex compant | No load | | 4 | 7 | mA |
| Idd | Supply current | V _{SYNC} =0V, No load | | 5 | 8 | mA |
| Vdd | Supply voltage | Idd peak < 2A | | | 16 | V |
| Vdd on | Enable voltage | · | 9.0 | 10.0 | 11.0 | V |
| SYNC REFI | ERENCE (SYNC) | | | | | |
| Vshth | SYNC high threshold | | | 3.9 | | V |
| Vslth | SYNC low threshold | | | 0.9 | | V |
| Vsync | SYNC clamp voltage | Isync=3mA | | 5 | | V |
| Isync | SYNC input current | | | | 3 | mA |
| Voltage Regu | ulator REFERENCE (VR) | | | | | |
| Ivr | VR Output Current | | | | 20 | mA |
| ON TIME D | OUTY SETUP (PIN 6) | | | | | |
| Ton-time | | | | 20 | | us |
| MOSFET G | ATE DRIVER (MOSG-C) | | | | | |
| Voh | Output high voltage | Io = -200 mA | 10.5 | 11 | | V |
| Vol | Output low voltage | Io = 200mA | | 0.5 | 0.8 | V |
| Td | Propagation delay | No load | 50 | 80 | | ns |
| Tpred | | No load | | 120 | | ns |
| Tr | Rise time | No load | | 10 | 25 | ns |
| Tf | Fall time | No load | | 10 | 25 | ns |
| Dynamic Pro | otect | | • | • | | - |
| Dt | Dynamic variable | Pin 4 open | | 600 | | ns |
| Ton-min | MOSG-C on time | PWM adjusts time > Dt | | 1 | | us |

^(*) Tr & Tf are measured among 10% and 90% of starting and final voltage.



PERFORMANCE CHARACTERISTICS (T_A=25°C, unless otherwise specified.)

Figure 1: Supply Current vs Supply Voltage

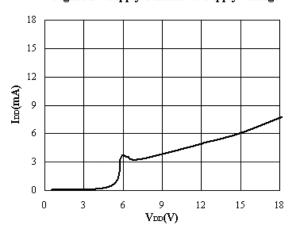
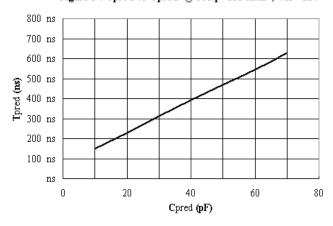
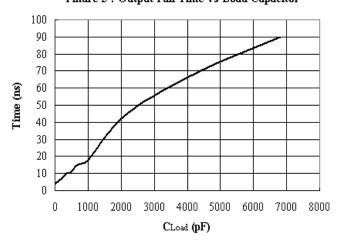


Figure 3 : Tpred vs Cpred @ Freq =100 KHz ; V_{1D} =10V



Fihure 5: Output Fall Time vs Load Capacitor



*Fig. 1 : No Load ; No SYNC *Fig. 4~5 : Frequency = 100 kHz.

Figure 2 : Supply Current vs Freq. @ No Load

6.5
6
5.5
8 4.5
4
3.5

Fihure 4: Output Rise Time vs Load Capacitor

200

Frequency (KHz)

250

300

350

400

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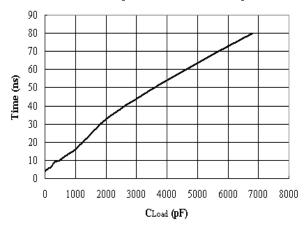
3

0

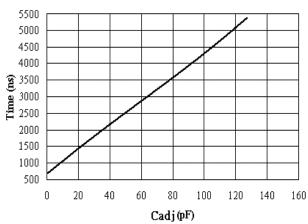
50

100

150

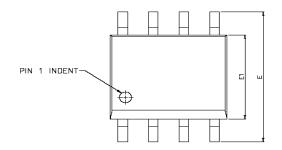


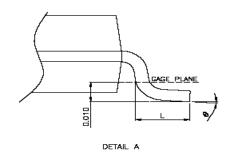
Fihure 6: Dynamic time vs Load Capacitor

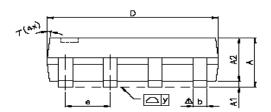


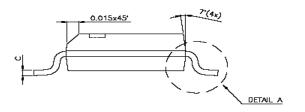


SOP- 8 PACKAGE OUTLINE









| 0,44501.0 | DIMENSIONS IN MILLIMETERS | | | DIMENSIONS IN INCHES | | |
|--------------|---------------------------|------|-------|----------------------|-------|--------|
| SYMBOLS | MIN | NOM | MAX | MIN | NOM | MAX |
| Α | 1.47 | 1.60 | 1.73 | 0.058 | 0.063 | 0.068 |
| A1 | 0.10 | | 0.25 | 0.004 | | 0.010 |
| A2 | | 1.45 | | | 0.057 | |
| Ь | 0.33 | 0.41 | 0.51 | 0.013 | 0.016 | 0.020 |
| С | 0.19 | 0.20 | 0.25 | 0.0075 | 0.008 | 0.0098 |
| D | 4.80 | 4.85 | 4.95 | 0.189 | 0.191 | 0.195 |
| Е | 5.80 | 6.00 | 6.20 | 0.228 | 0.236 | 0.244 |
| E1 | 3.80 | 3.90 | 4.00 | 0.150 | 0.154 | 0.157 |
| е | | 1.27 | | | 0.050 | |
| L | 0.38 | 0.71 | 1.27 | 0.015 | 0.028 | 0.050 |
| <u>∕</u> 2 y | | | 0.076 | | | 0.003 |
| 0 | 0, | | 8. | 0, | | 8* |



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